

RP-J

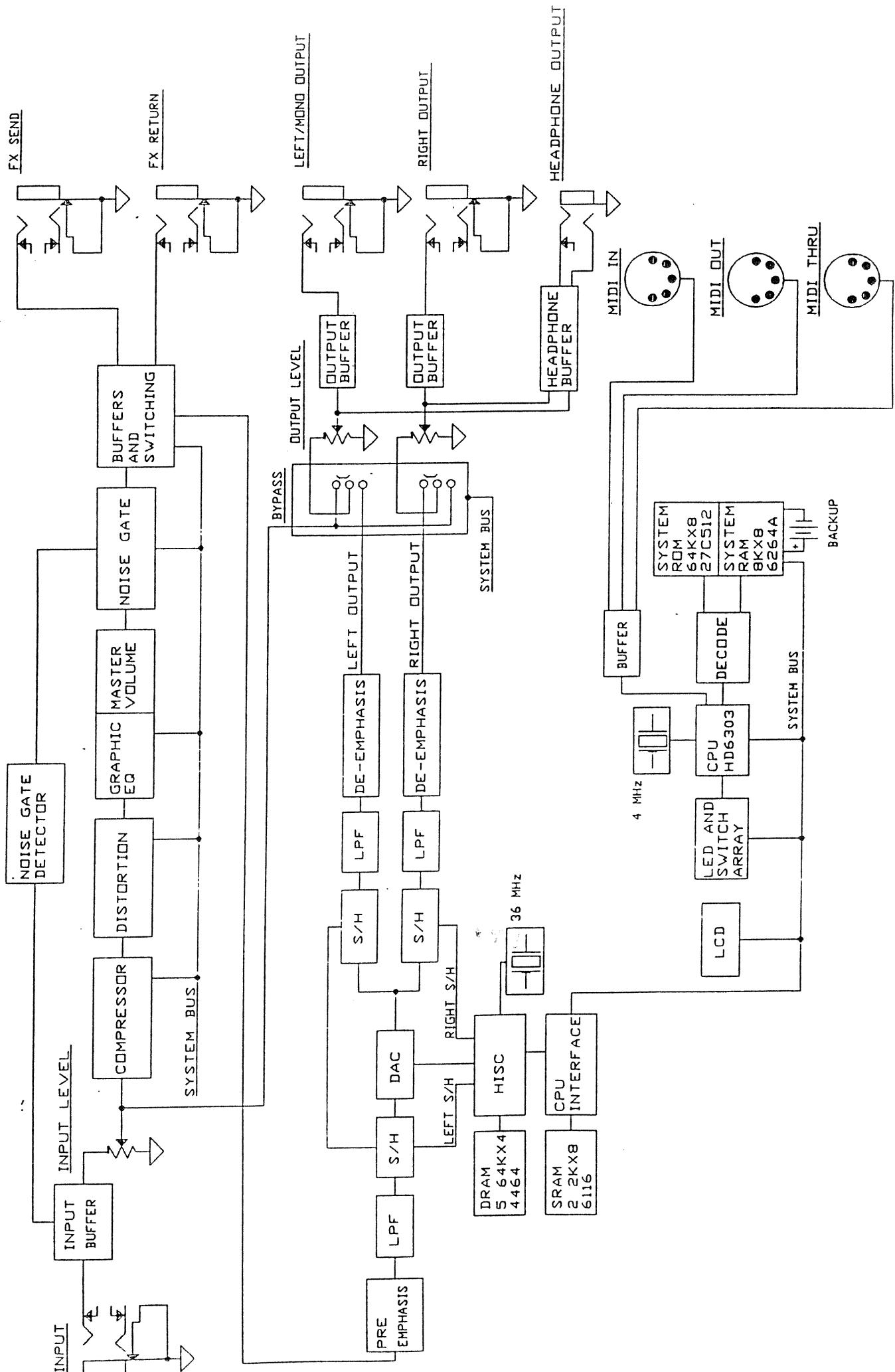
Service Manual

- **BLOCK DIAGRAM**
 - **SETUP PROCEDURES**
 - **SCHEMATIC DIAGRAMS**
 - **PARTS LISTS**
 - **PC BOARDS**
 - **HISC PINOUT**
 - **HISC PIN DESCRIPTIONS**



H A Harman International Company

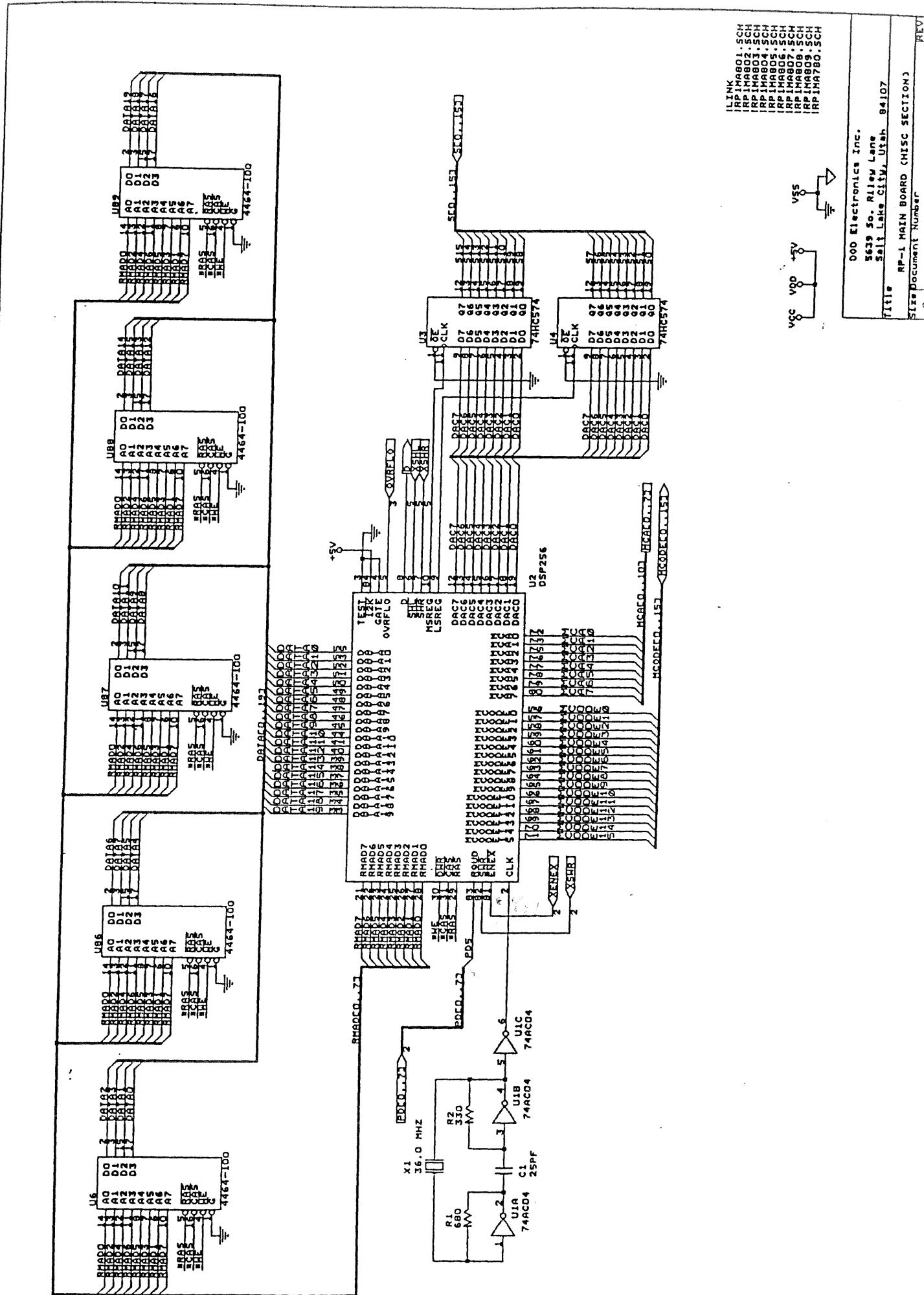
RPf : BLOCK DIAGRAM

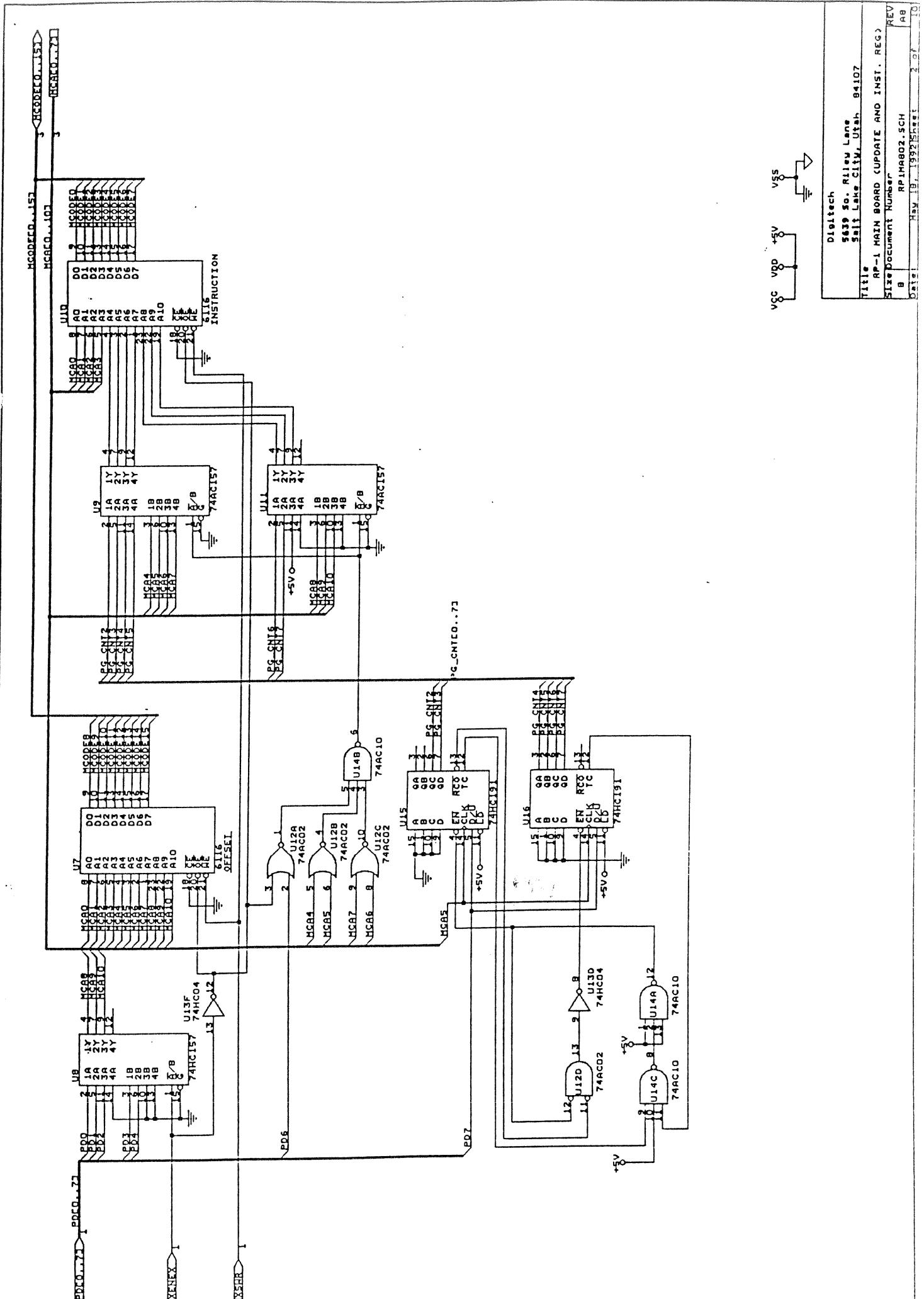


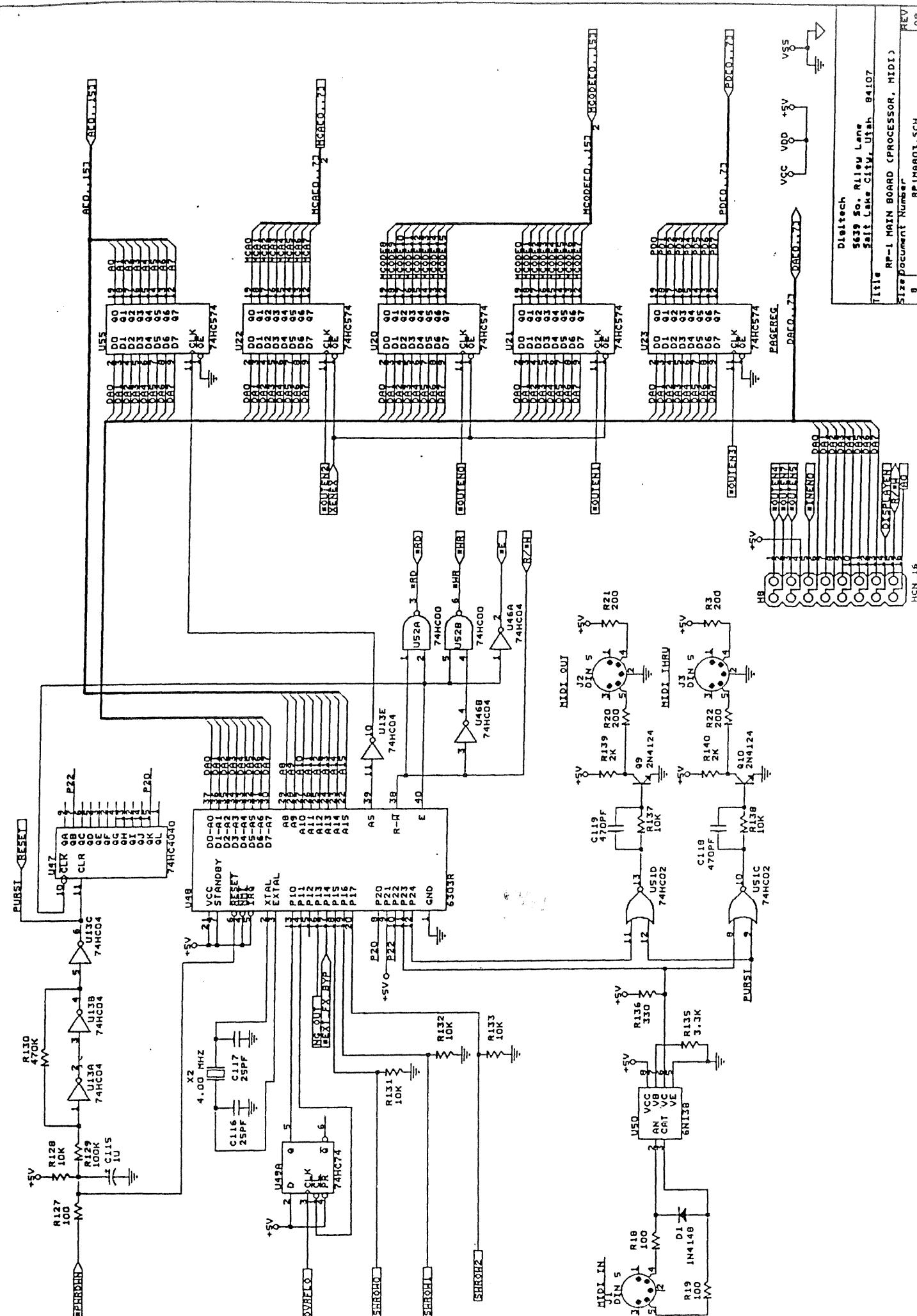
RP-1 Setup and Test Procedures

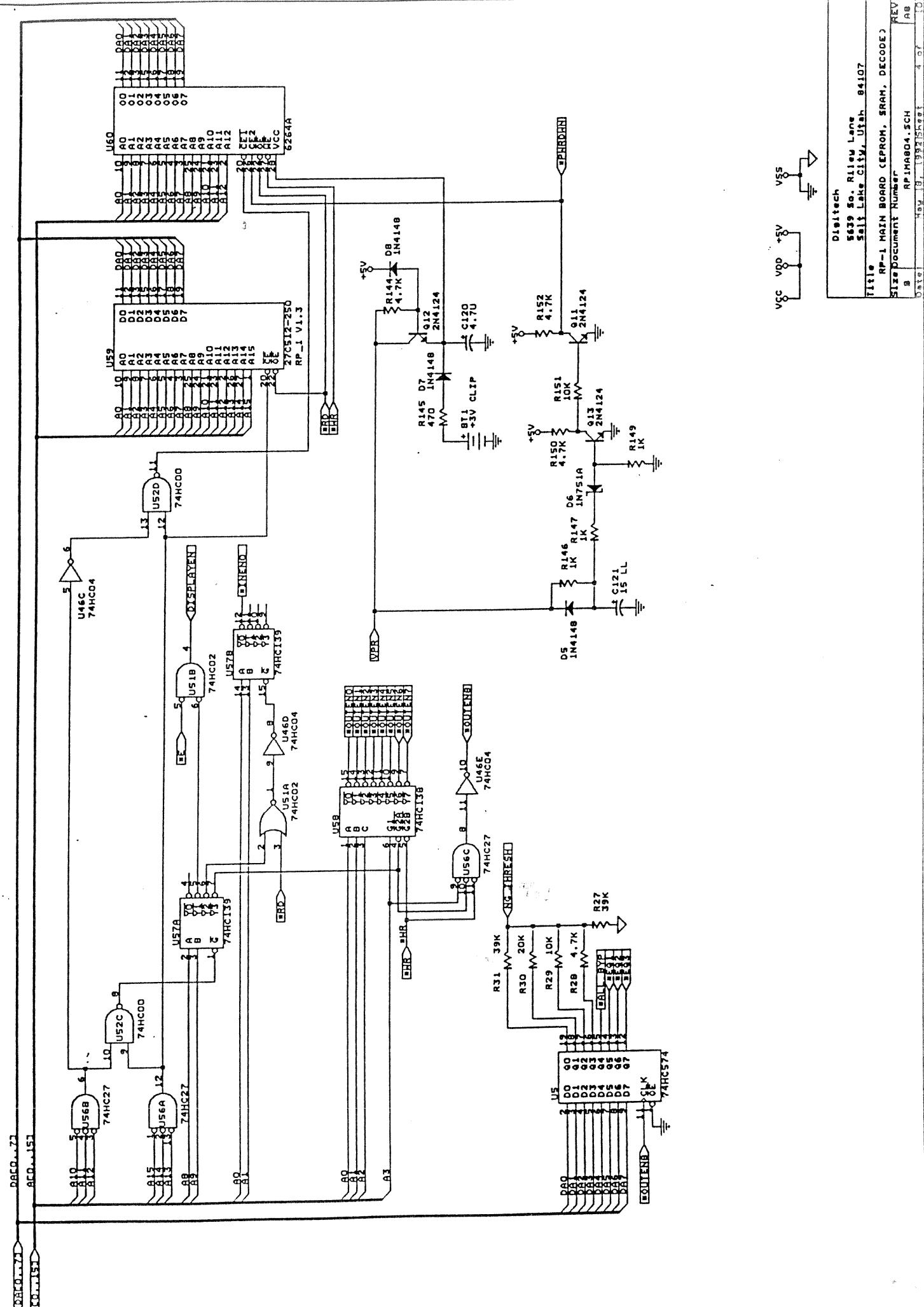
To access the RP-1 setup and test menus, enter the UTILITY mode and scroll left or right until the software version number is displayed. Press the parameter down button twice to enter the test menu. Scroll right to access the compressor gain trim, distortion gain trim, and A/D calibration programs. The procedures for these setup routines are detailed below. Further scrolling will show the EQ test, speaker simulator test, compression test, distortion test, noise gate test, HIS/C test, RAM test, and display tests. When done, return to the main utility menu.

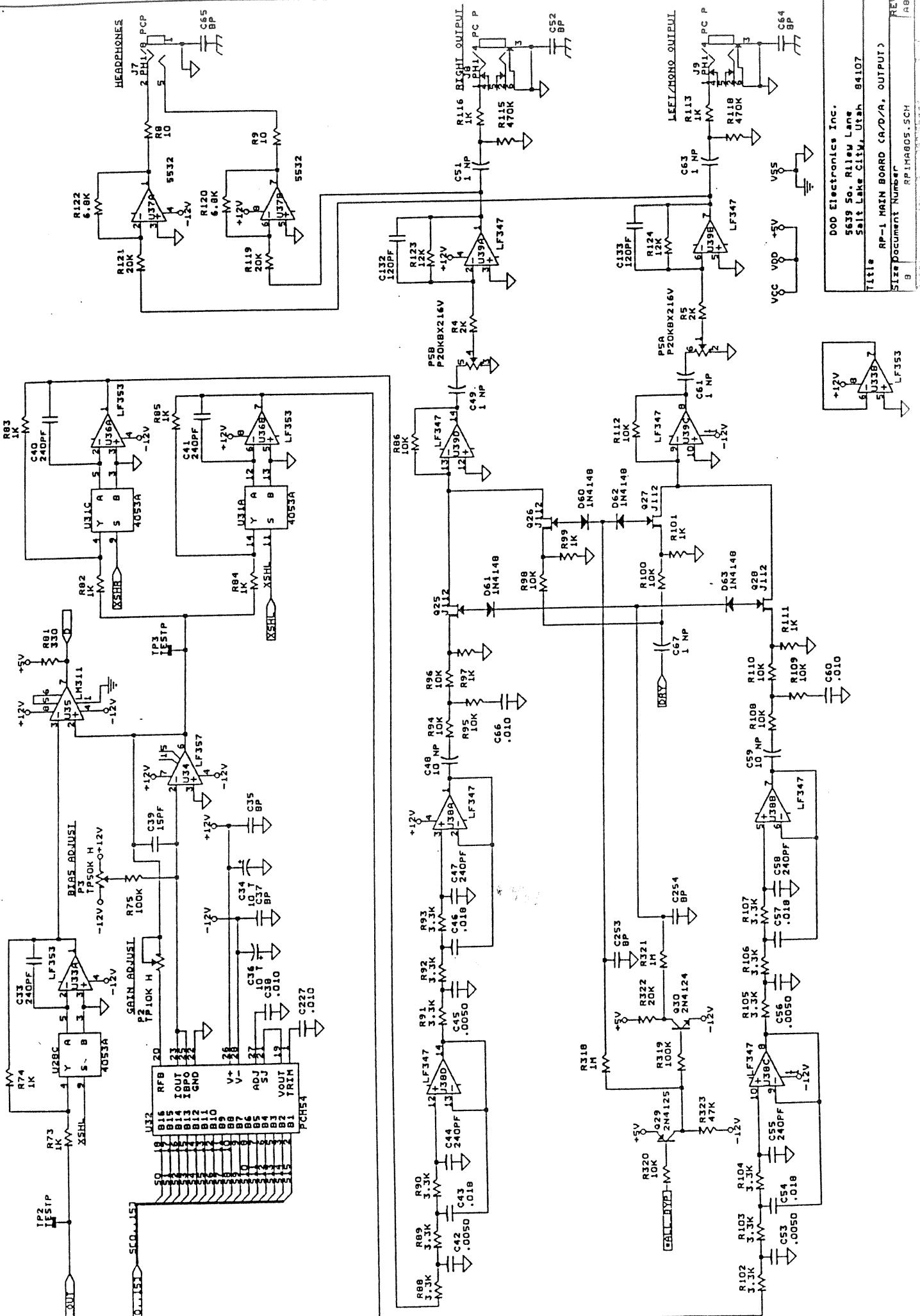
1. Compressor gain trim: With a 1 Vp-p, 1 KHz sine wave measured at test point one (TP1) on the main PCB, adjust P6 (50K trimpot) until the signal measured at TP4 is the same amplitude as the signal at TP1.
2. Distortion gain trim: Adjust P7 (50k trimpot) until the voltage measured at pin 7 of U97 is between -3mV DC and +3mV DC.
3. A/D Calibration a) Gain: With a 14 Vp-p, 1KHz sine wave measured at TP2, adjust P2 (10K trimpot) until the signal measured at TP3 is 14 Vp-p.
b) Bias: Reduce the signal level 50 dB to 44.3 mVp-p and adjust P3 (50K trimpot) until the signal seen at TP3 is just barely all positive going or all negative going.

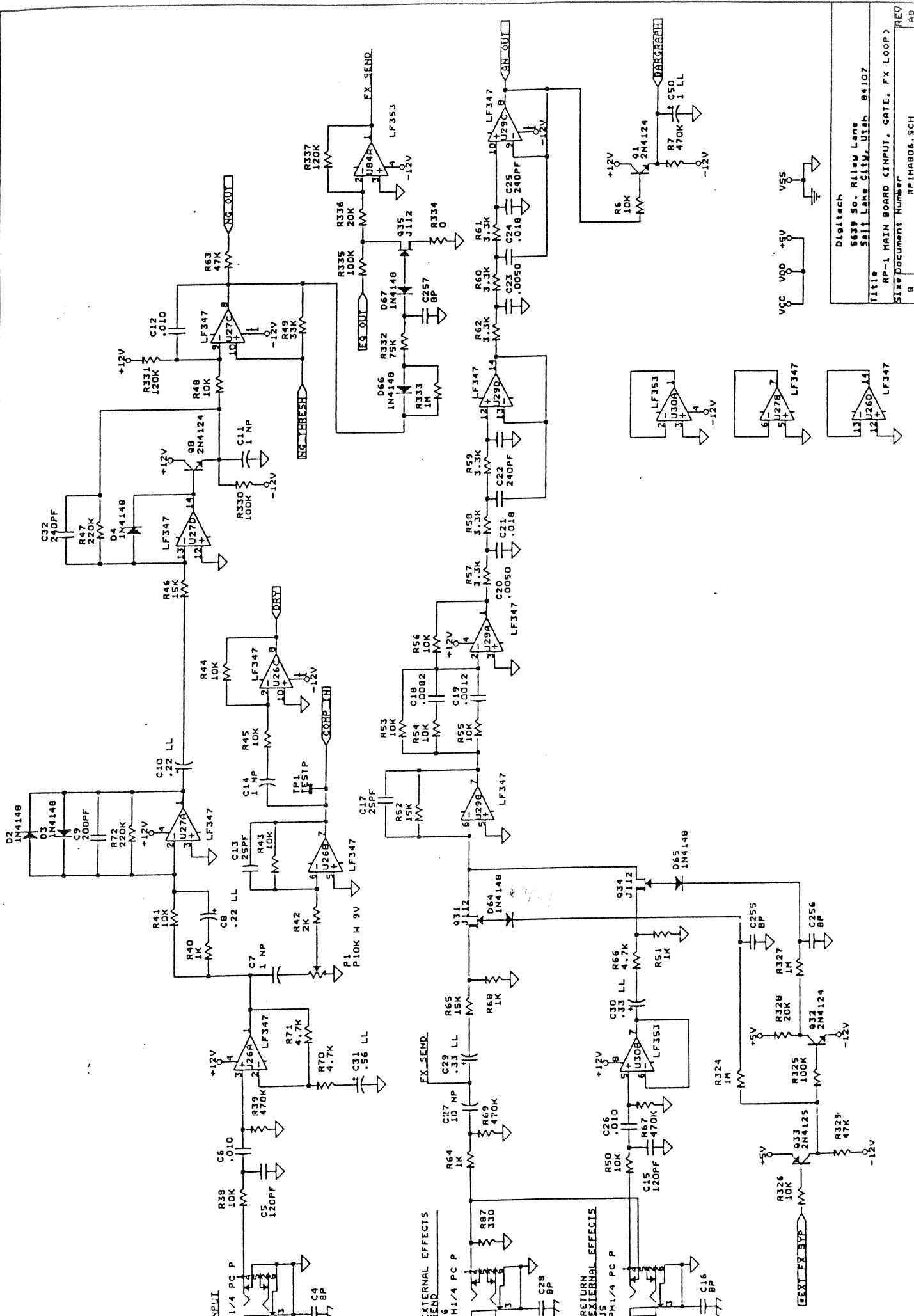


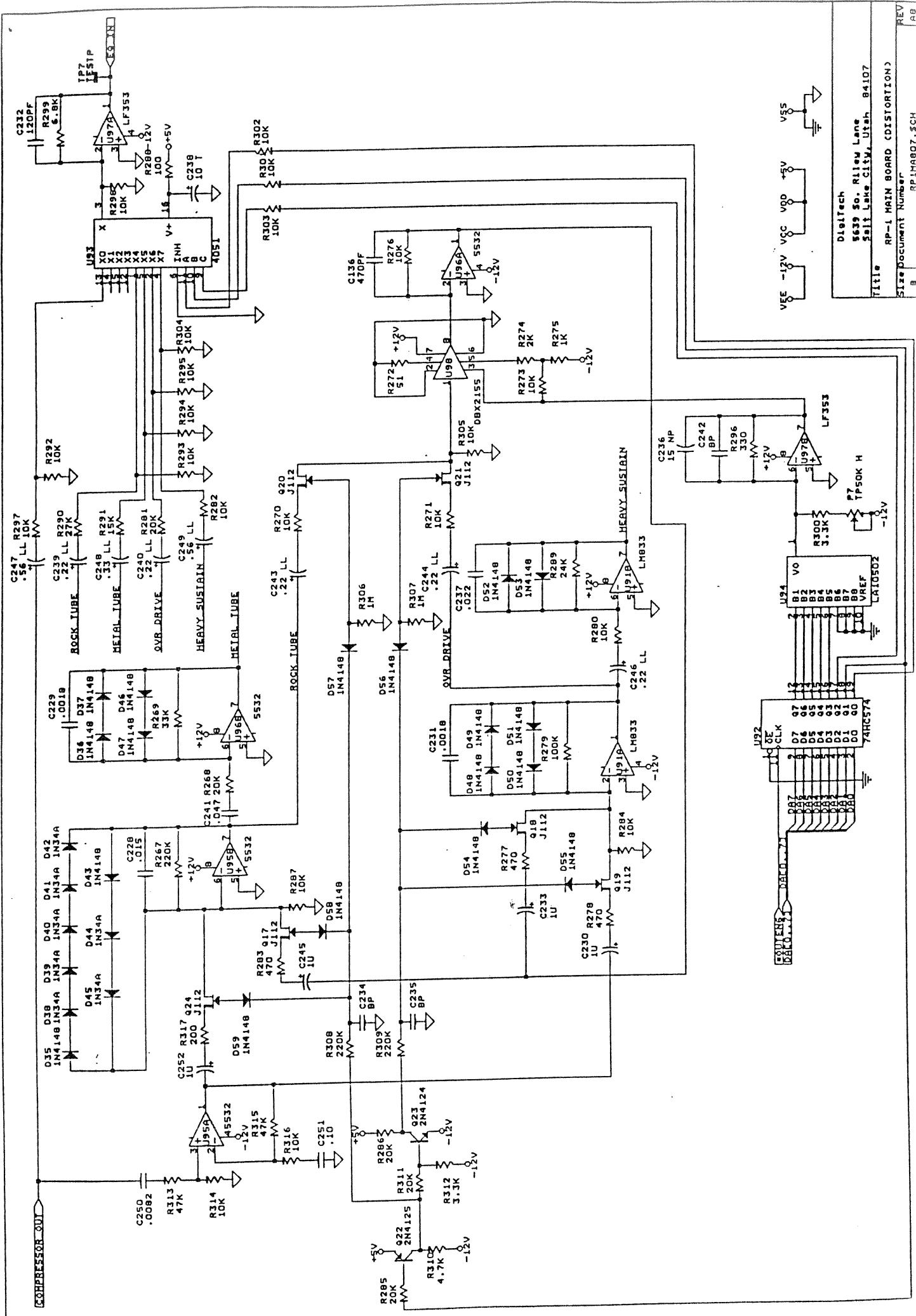


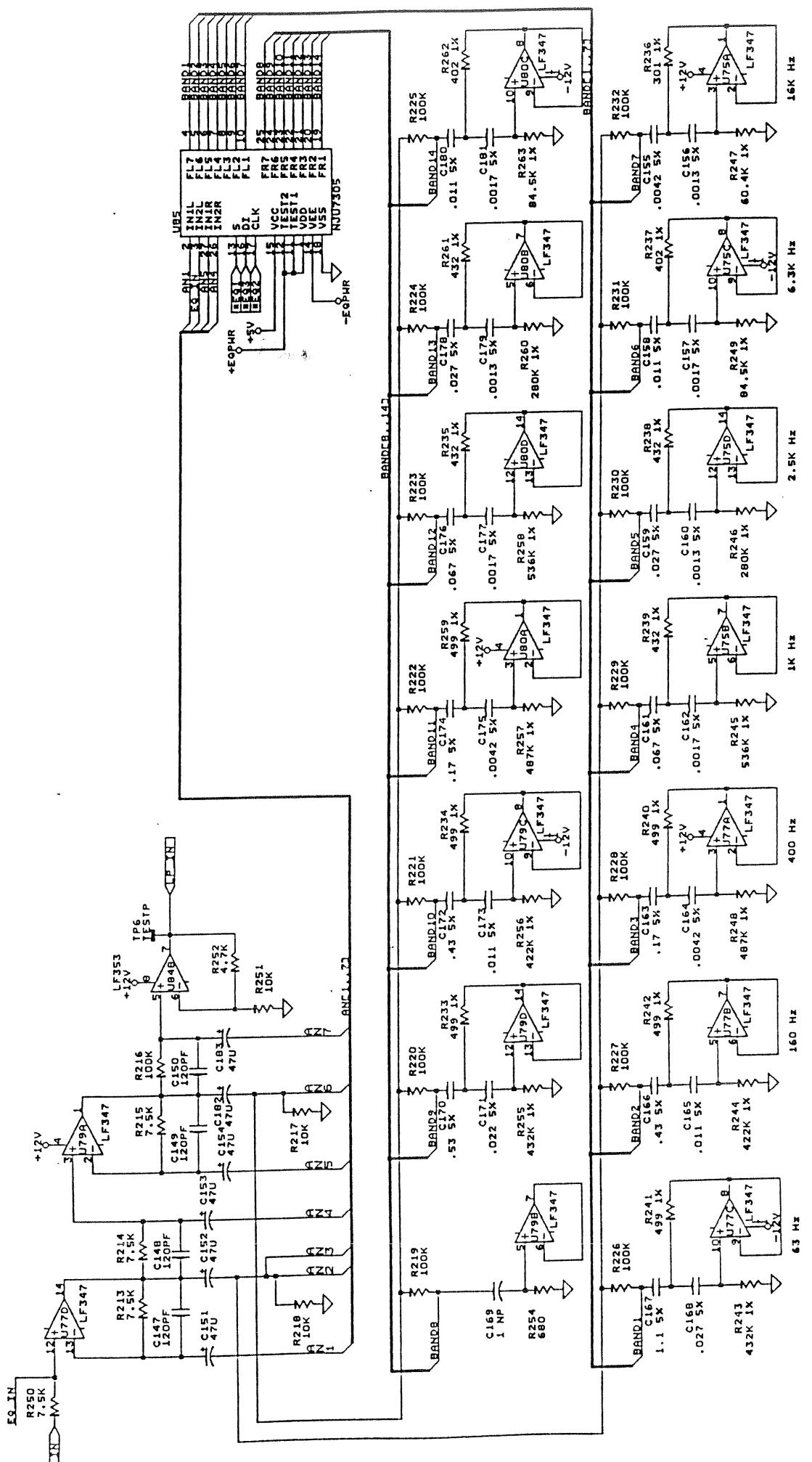




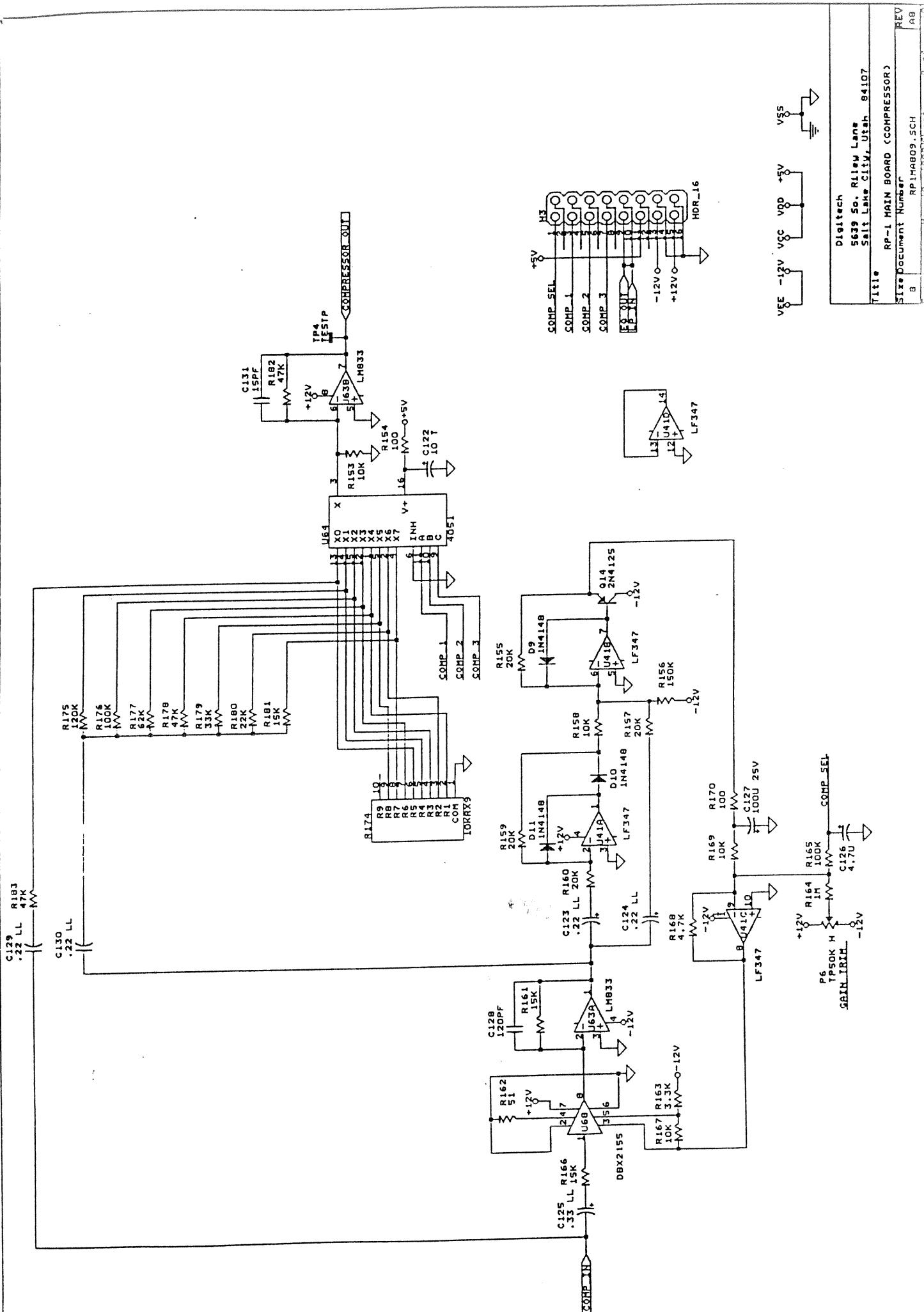




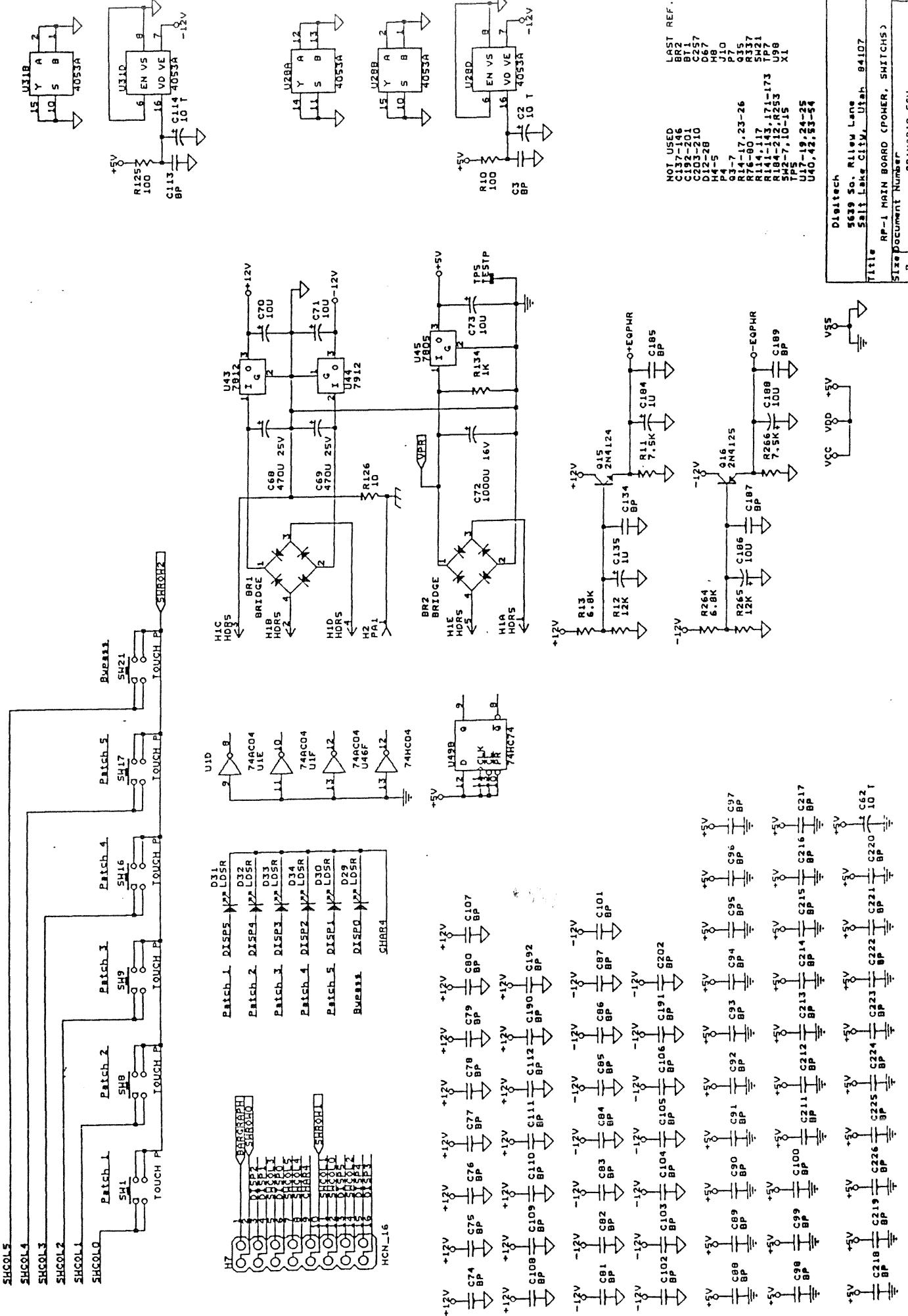




DOD Electronics, Inc.
5639 So. Riley Lane,
Salt Lake City, Utah, 84107
Title: RP-1 MAIN BOARD (GRAPHIC EQ)
Size Document Number: RP1HAB08.SCH
Date: May 18, 1982
Rev: B
Page: 10
Page 10 of 10



REV A8
Digitel
5019 So., River Lane
Salt Lake City, Utah 84107
Title: RP-1 MAIN BOARD (COMPRESSOR)
Six# Document Number: RP1MAB03.SCH

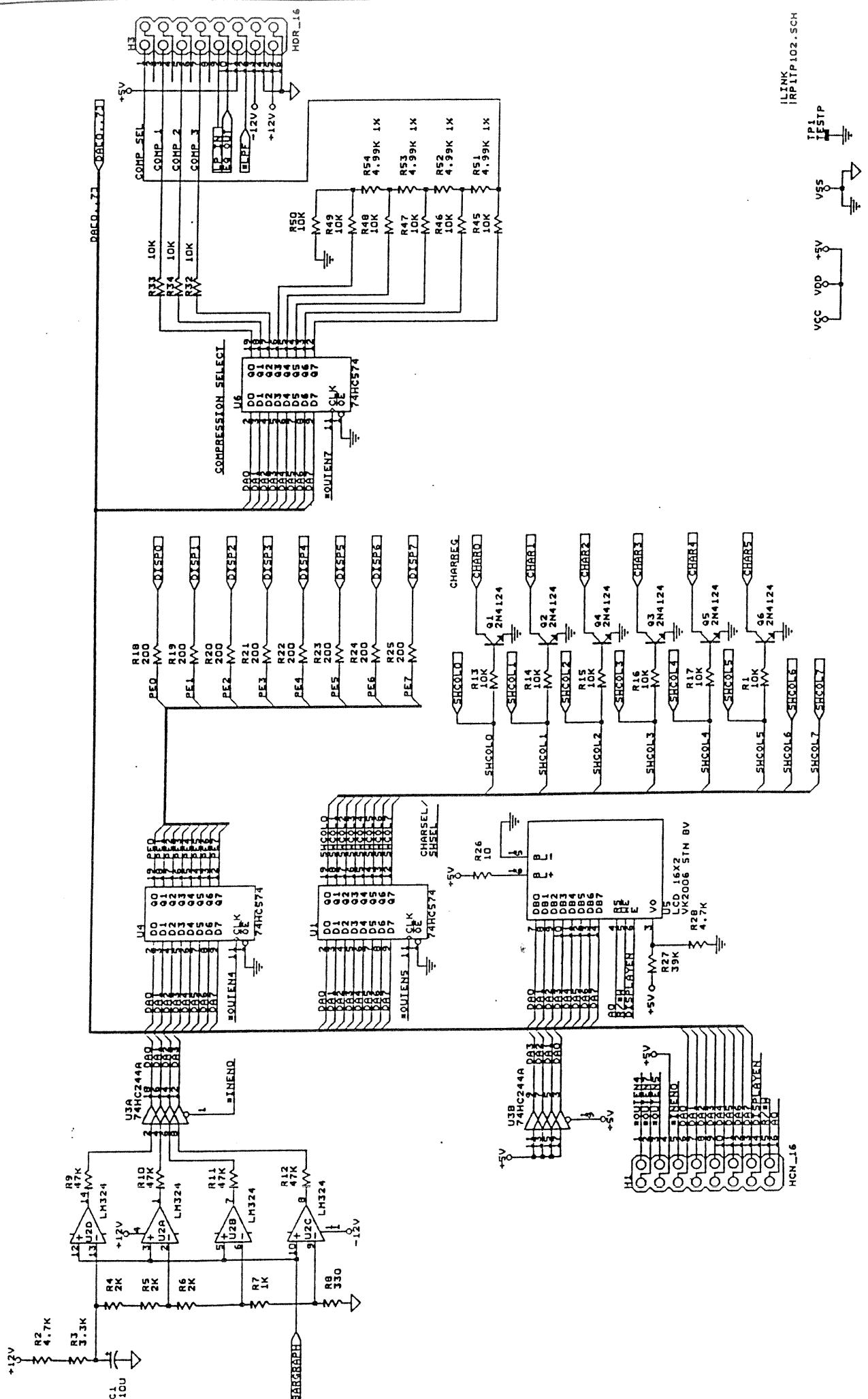


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Size/cols Document Number	RP1MBA10.SCH
Date	Rev A May 18, 1993
Page	10 of 10

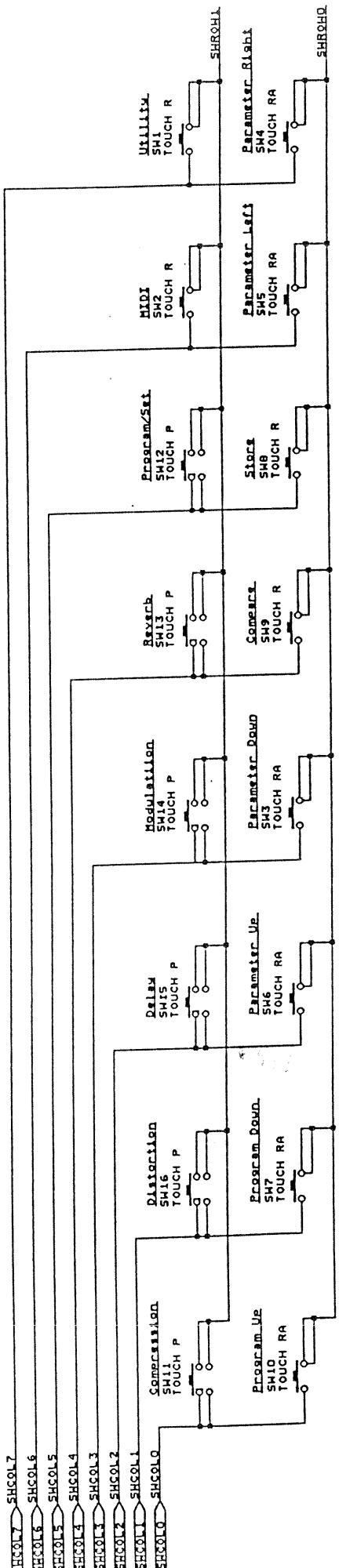
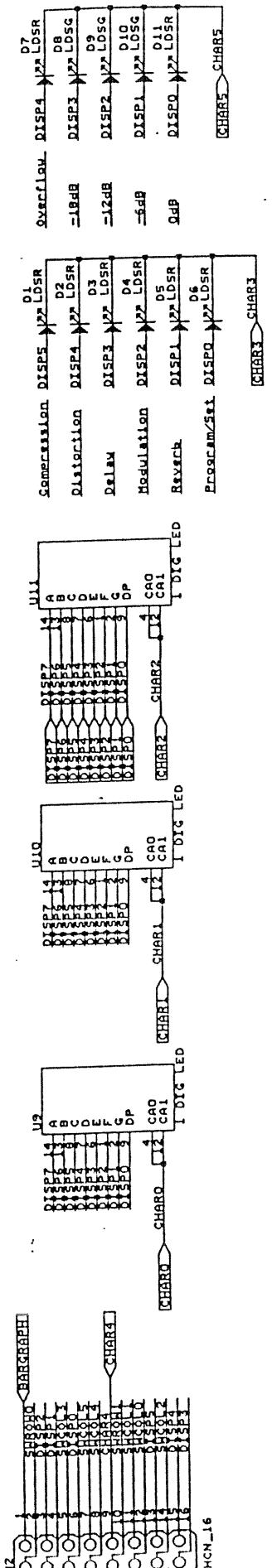
Sheet 18 of 19

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REV A



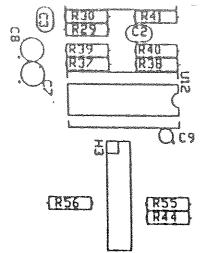
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Size: 9
Page: 107
Date: 5/15/2007
Rev: A0



NOT USED LAST REF

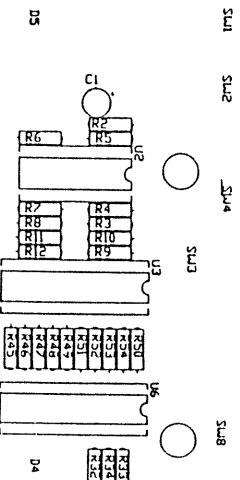
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Digitel		5659 So. Rillie Lane Salt Lake City, Utah 84107	

80-5028-A
REV A

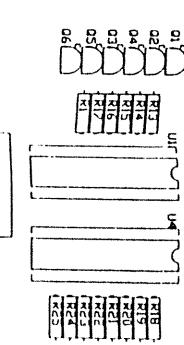


All Components With Out Outlines Get Installed On Solder Side

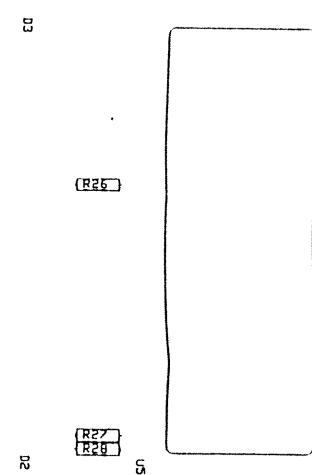
SW13



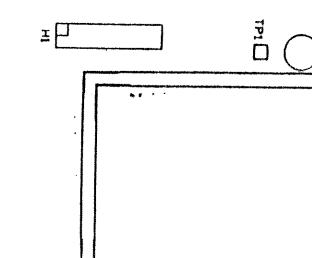
SW14



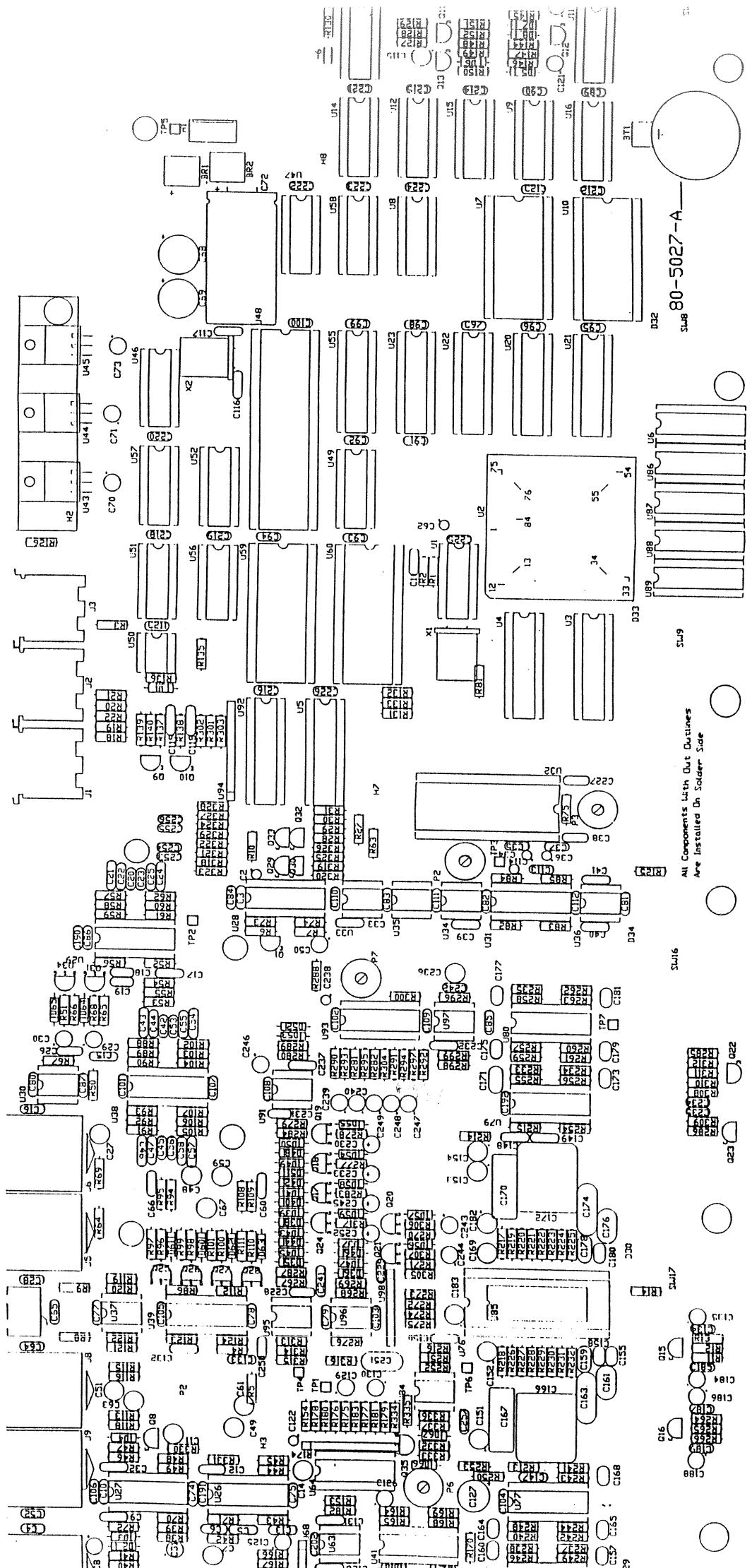
SW15

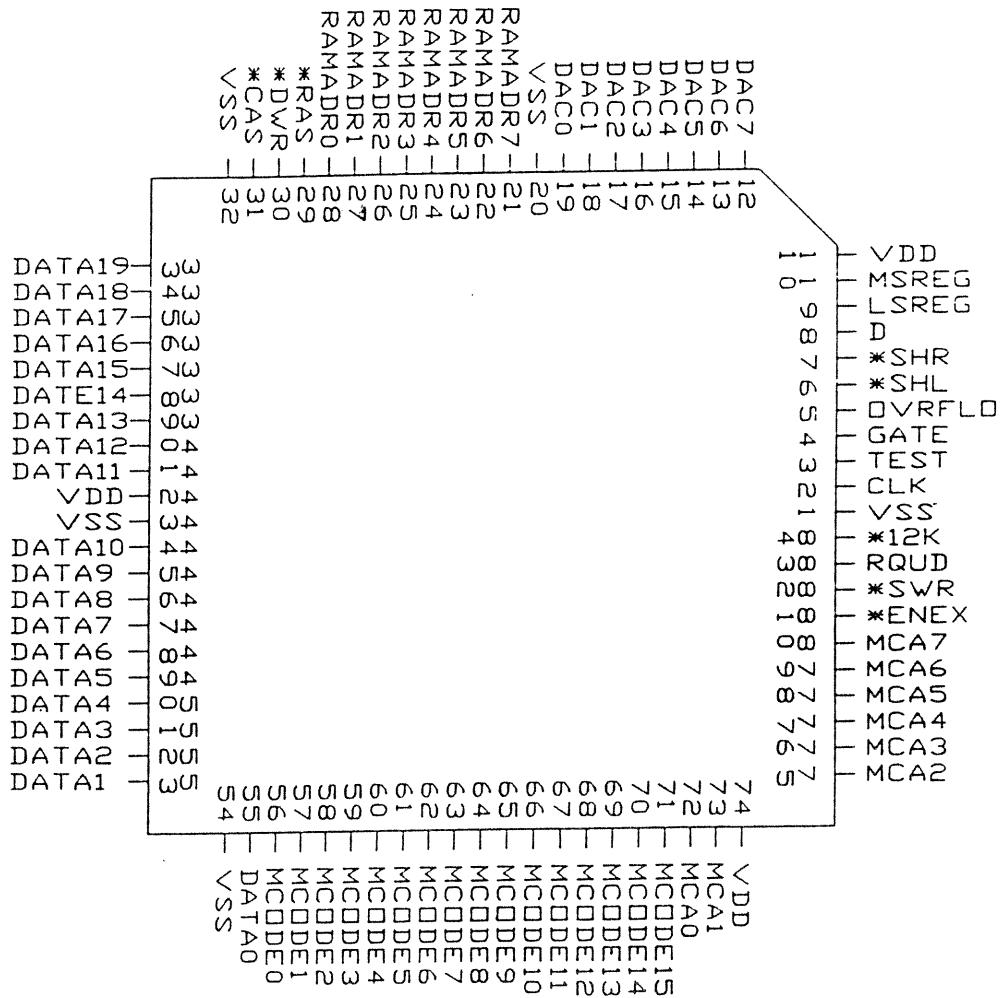


SW16



SW17





FUNCTIONAL PIN DESCRIPTION FOR HISC

<u>Description</u>	<u>Pin</u>
VSS: ground (GND)	1,20,32,43,54
CLK: oscillator input	2
TEST: in-house test only (GND)	3
GATE: in-house test only (GND)	4
OVRFL0: indicates internal math overflow	5
SHL: sample/hold left	6
SHR: sample/hold right	7
D: DAC compare input	8
LSREG: clocks lower byte DAC output	9
MSREG: clocks upper byte DAC output	10
VDD: +5V power	11,42,74
DAC7..DAC0: DAC output data	12,13,14,15,16,17 18,19
RAMADR7..RAMADR0: DRAM address output	21,22,23,24,25,26 27,28
RAS: DRAM row address strobe	29
DWR: DRAM write	30
CAS: DRAM column address strobe	31
DATA19..DATA0: DRAM data	33,34,35,36,37,38, 39,40,41,44,45,46, 47,48,49,50,51,52, 53,55
MCODE0..MCODE15: microcode data	56,57,58,59,60,61, 62,63,64,65,66,67, 68,69,70,71
MCA0..MCA7: microcode address	72,73,75,76,77,78, 79,80
ENEX: enable external microcode write	81
SWR: external microcode write line	82
RQUD: request for microcode update	83
12K: in-house test only (+5V)	84